Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]
HP ProDesk 680 G4 PCI Microtower Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment
1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>250W, EPA92 Acbel</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
</tbody>
</table>
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations.

Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Pull the latch and remove access panel
2. Pull the HDD latch from HDD cage
3. Disconnect SATA/Power cables from the HDD.
4. Disconnect SATA/Power cables from slim ODD.
5. Remove main bezel from chassis
6. Remove HDD cage from the chassis
7. Press slim ODD latch
8. Remove slim ODD from ODD cage
9. Disconnect HDD SATA cable from the MB.
10. Disconnect HDD Power cable from the MB
11. Disconnect P1 Power cable from the MB
12. Disconnect P2 Power cable from the MB
13. Disconnect speaker cable from the MB
14. Disconnect CPU power cable from the MB
15. Disconnect ODD power cable from the MB
16. Disconnect ODD SATA cable from the MB
17. Poke clip and remove SATA & power cables
18. Disconnect heat sink cable from the MB
19. Disconnect system fan cable from the MB
20. Use T-15 screwdriver to loose the screws and remove heat sink
21. Use PH1 screwdriver to loose the screws and remove the fan
22. Separate the fan from CPU heat sink
23. Disconnect memory from the MB
24. Rotate the handle and open it up
25. Remove CPU from MB
26. Remove the battery from the MB
27. Use T-15 to loose the screws of MB
28. Remove MB from chassis
29. Use PH1 screwdriver to loose screws of system fan and remove it
30. Use T-15 screwdriver to loose the screws of speaker and remove it
31. Use 170II micro shear to cut two cable ties of PSU cables from chassis
32. Use T-15 screwdriver to loose the screws of PSU
33. Press PSU latch and remove it
34. Cut the cable tie
35. Remove screw for bottom
36. Remove screw for top
37. Remove cover
38. Remove FG screw
39. Disconnect fan connector and inlet connector.
40. Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1 Pull the latch and remove access panel

Figure 2 Pull the HDD latch from HDD cage

Figure 3 Disconnect SATA/Power cables from the HDD

Figure 4 Disconnect SATA/Power cables from slim ODD

Figure 5 Remove main bezel from chassis

Figure 6 Remove HDD cage from the chassis

PSG instructions for this template are available at EL-MF877-01
Figure 7 Press slim ODD latch

Figure 8 Remove slim ODD from ODD cage

Figure 9 Disconnect HDD SATA cable from the MB

Figure 10 Disconnect HDD Power cable from the MB

Figure 11 Disconnect P1 Power cable from the MB

Figure 12 Disconnect P2 Power cable from the MB
Figure 13 Disconnect speaker cable from the MB
Figure 14 Disconnect CPU power cable from the MB
Figure 15 Disconnect ODD power cable from the MB
Figure 16 Disconnect ODD SATA cable from the MB
Figure 17 Poke clip and remove SATA & power cables
Figure 18 Disconnect heat sink cable from the MB
Figure 19 Disconnect system fan cable from the MB

Figure 20 Use T-15 screwdriver to loose the screws and remove heat sink

Figure 21 Use PH1 screwdriver to loose the screws and remove the fan

Figure 22 Separate the fan from CPU heat sink
Figure 23 Disconnect memory from the MB

Figure 24 Rotate the handle and open it up

Figure 25 Remove CPU from MB

Figure 26 Remove the battery from the MB

Figure 27 Use T-15 to loose the screws of MB

Figure 28 Remove MB from chassis
| Figure 29 | Use PH1 screwdriver to loose screws of system fan and remove it |
| Figure 30 | Use T-15 screwdriver to loose the screws of speaker and remove it |
| Figure 31 | Use 170II micro shear to cut two cable ties of PSU cables from chassis |
| Figure 32 | Use T-15 screwdriver to loose the screws of PSU |

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 33 Press PSU latch and remove it

Figure 34 Cut the cable tie

Figure 35 Remove screw for bottom

Figure 36 Remove screw for top

Figure 37 Remove cover

Figure 38 Remove FG screw
<table>
<thead>
<tr>
<th>Figure</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>39</td>
<td>Disconnect fan connector and inlet connector.</td>
</tr>
<tr>
<td>40</td>
<td>Remove PCB1 screw</td>
</tr>
<tr>
<td>41</td>
<td>Remove AC inlet &amp; Fan screw</td>
</tr>
<tr>
<td>42</td>
<td>Heat the solder of Electrolytic Capacitors greater than 2.5cm in diameter or height and remove it.</td>
</tr>
</tbody>
</table>

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